Technical Data Sheet

FeedBond® EP-2009-J6A

B-Stage WBC Adhesive

Introduction:

EP-2009-J6A is B-stage type adhesive which designed for WBC process use in stencil / screen printing. This material is ideal for chip scale packages where tolerance and bleed need to be minimized. EP-2009-J6A is a low modulus adhesive ideal for large die sizes.

Features:

- Applicable for WBC process
- Stencil / Screen printing
- Low warpage

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Density	1.4 g/cc	Pycnometer	FT-P001
Appearance	White		
Viscosity @ 25℃	50000 cps	Brookfield DV-Ⅲ/CP-51 @ 5rpm	FT-P006
Thixotropic Index @ 25℃	1.4	Brookfield DV-Ⅲ/CP-51 Vis. @ 0.5rpm/Vis. @ 5rpm	FT-P008
Grind	＜20μm	Grind meter	FT-P025
Work Life @ 25℃	24hr		FT-P024
Shelf Life @ -40℃	6 months		FT-P018
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
B-stage Cure Condition		Ramp 25℃ to 100℃ 30 minutes. Hold 100℃ 60 minutes and cool down to 25℃ 30 minutes.	
C-stage Cure Condition		30~60 minutes @175℃	
MECHANICAL PROPERTIES-POST CURE		TEST DESCRIPTION	TEST METHOD
Die Shear Strength @ 25℃	>4 Kg/die	45x45mil Si die on Glass	FT-M012
Die Shear Strength @ 175℃	>3Kg/die	45x45mil Si die on Glass	FT-M012

The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

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PHYSIOCHEMICAL PROPERTIES-POST CURE		TEST DESCRIPTION	TEST METHOD
Volume Resistivity	0.5 X 10^{14} Ω · cm		FT-P039
Glass Transition Temperature	86℃	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion		TMA Expansion Mode	FT-M016
Below Tg	7 ppm/℃		
Above Tg	259 ppm/℃		
Dynamic Tensile Modulus			FT-M019
@25℃	2342 MPa	Dynamic Mechanical Thermal Analysis Using <1.5 mm Thick Specimen	
@150℃	121 MPa		
@250℃	102 MPa		
Ionic Content			
Cl^-	<15 ppm	Teflon Flask, 5 g Sample in 50g DI Water, 24 hours @100℃	FT-C021
Na^+	<10 ppm		
K^+	<10 ppm		

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Instruction

Thawing

Place the container to stand vertically for 30~60mins.**DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

Storage

Adhesive should be stored @ -20~ -40°C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Availability

FeedBond® adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.